

Description

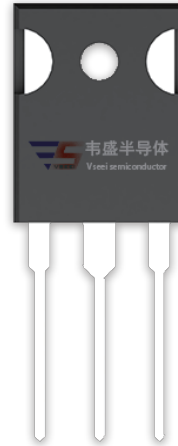
The VSM210N08 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in automotive applications and a wide variety of other applications.

General Features

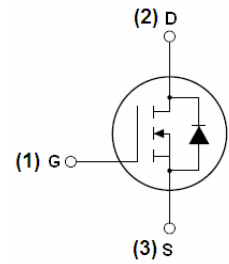
- $V_{DSS} = 85V, I_D = 210A$
 $R_{DS(ON)} < 3.5m\Omega @ V_{GS} = 10V$
- Good stability and uniformity with high E_{AS}
- Special process technology for high ESD capability
- High density cell design for ultra low R_{dson}
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

Application

- Automotive applications
- Hard switched and high frequency circuits
- Uninterruptible power supply



TO-247



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM210N08-T7	VSM210N08	TO-247	-	-	-

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DSS}	85	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	210	A
Drain Current-Continuous($T_C = 100^\circ C$)	$I_D (100^\circ C)$	150	A
Pulsed Drain Current	I_{DM}	850	A
Maximum Power Dissipation	P_D	330	W
Derating factor		2.2	W/ $^\circ C$
Single pulse avalanche energy ^(Note 3)	E_{AS}	2200	mJ
Peak Diode Recovery dv/dt ^(Note 4)	dv/dt	5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 1)	$R_{\theta JC}$	0.45	$^{\circ}\text{C/W}$
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Electrical Characteristics ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

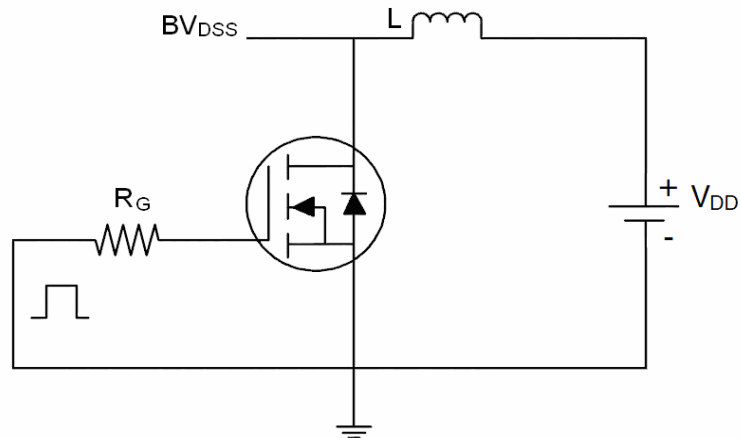
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	85	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =85V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±200	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =40A	-	2.9	3.5	mΩ
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =20A	35	-	-	S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, F=1.0MHz	-	11000	-	PF
Output Capacitance	C _{oss}		-	914	-	PF
Reverse Transfer Capacitance	C _{rss}		-	695	-	PF
Switching Characteristics						
Turn-on Delay Time	t _{d(on)}	V _{DD} =30V, I _D =2A, R _L =15Ω V _{GS} =10V, R _G =2.5Ω	-	23	-	nS
Turn-on Rise Time	t _r		-	190	-	nS
Turn-Off Delay Time	t _{d(off)}		-	130	-	nS
Turn-Off Fall Time	t _f		-	120	-	nS
Total Gate Charge	Q _g	ID=30A, VDD=30V, VGS=10V	-	250	-	nC
Gate-Source Charge	Q _{gs}		-	48	-	nC
Gate-Drain Charge	Q _{gd}		-	98	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =40A	-	-	1.2	V
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 40A di/dt = 100A/μs ^(Note2)	-	63	-	nS
Reverse Recovery Charge	Q _{rr}		-	98	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

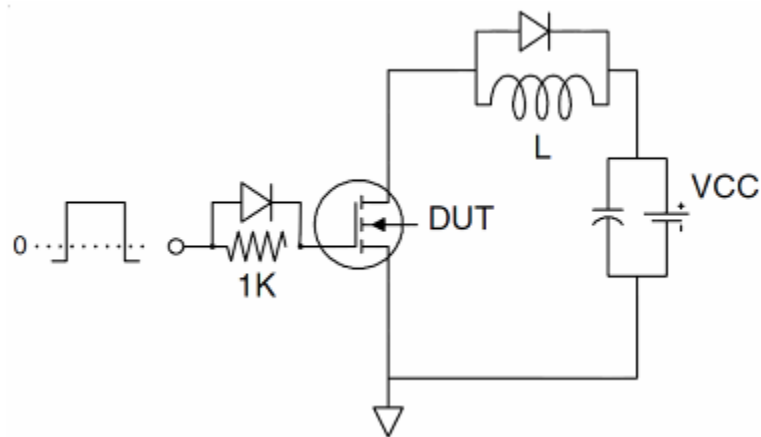
1. Surface Mounted on FR4 Board, $t \leq 10$ sec.
2. Pulse Test: Pulse Width $\leq 400\mu s$, Duty Cycle $\leq 2\%$.
3. EAS condition: $T_J=25^{\circ}\text{C}, V_{DD}=42.5V, V_G=10V, L=2mH, R_g=25\Omega, I_{AS}=37A$
4. $I_{SD} \leq 125A, di/dt \leq 260A/\mu s, V_{DD} \leq V_{(BR)PSS}, T_J \leq 175^{\circ}\text{C}$

Test Circuit

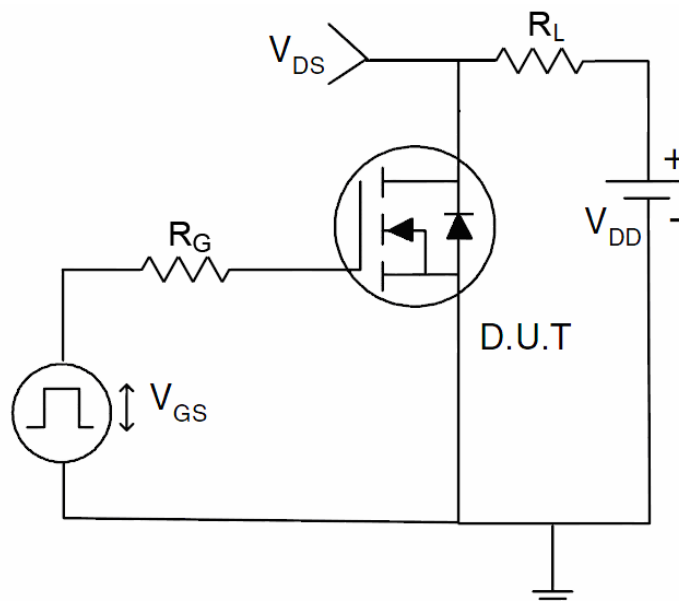
1) E_{AS} test Circuit



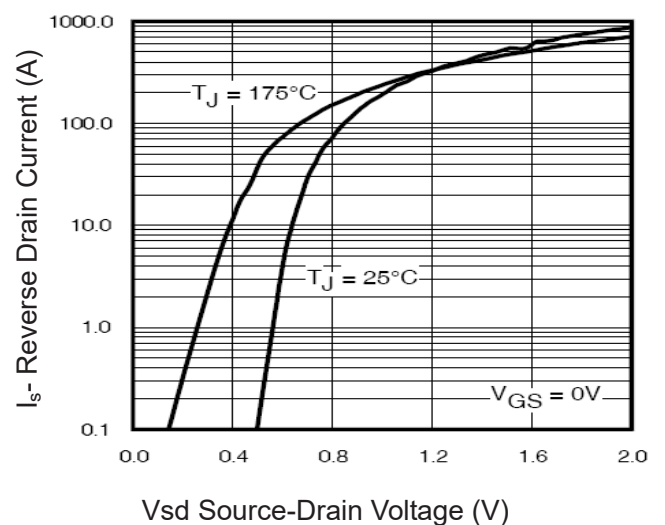
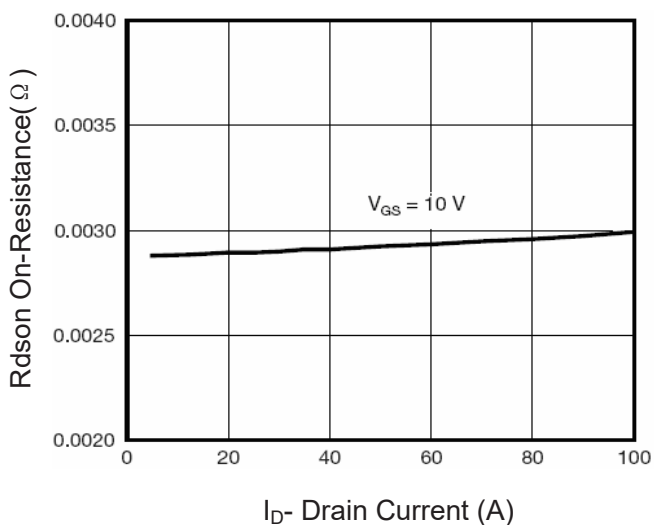
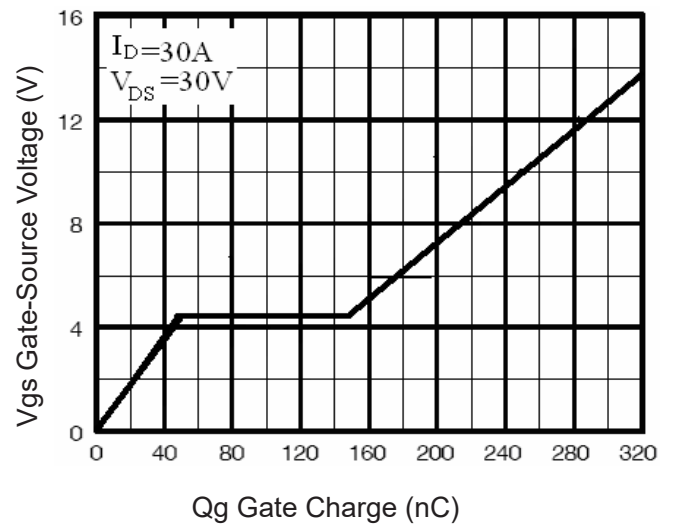
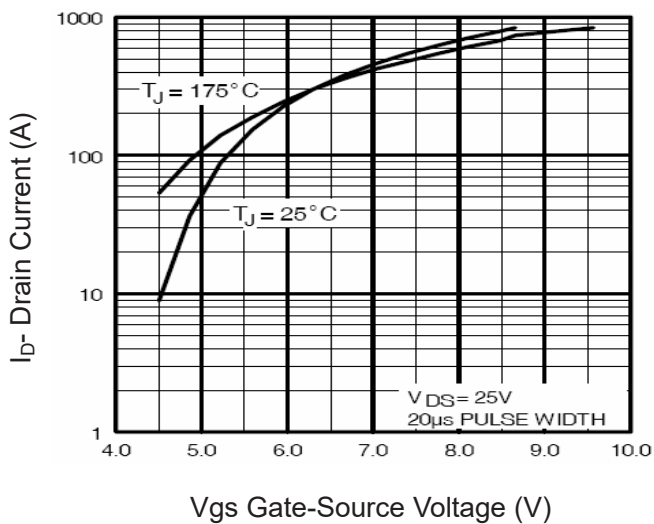
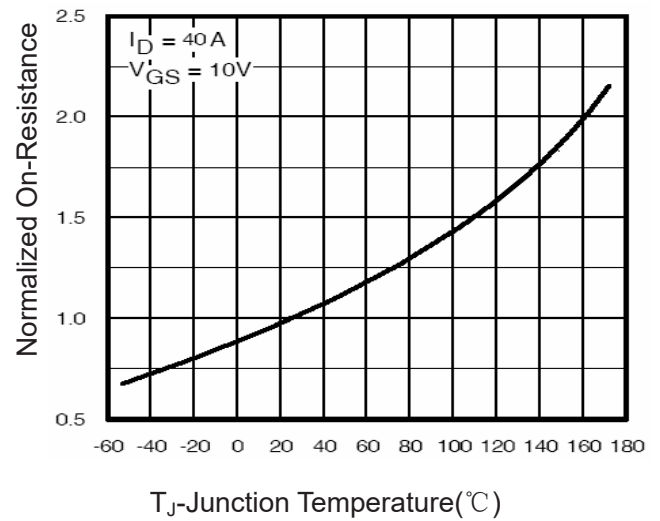
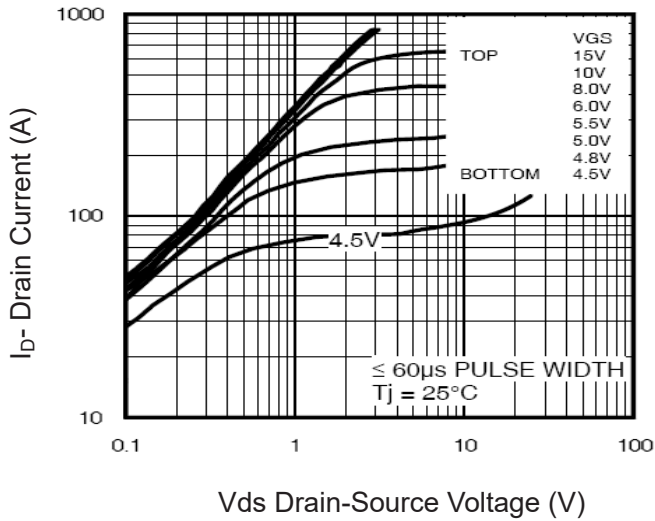
2) Gate charge test Circuit

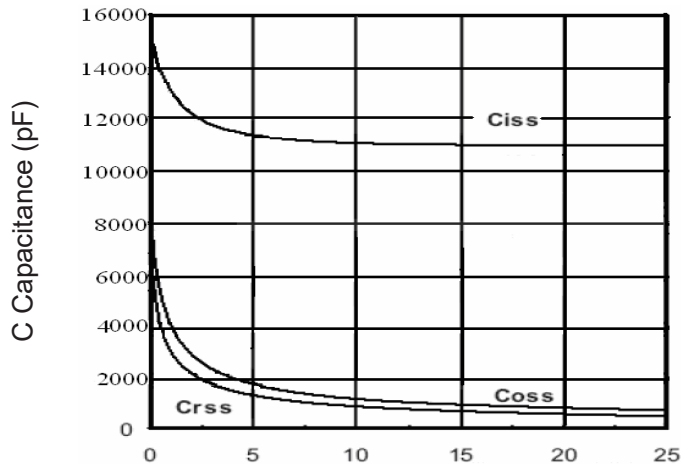


3) Switch Time Test Circuit

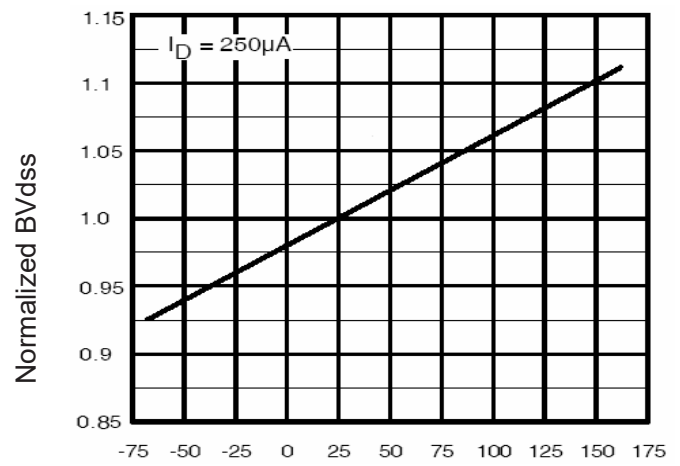


Typical Electrical and Thermal Characteristics

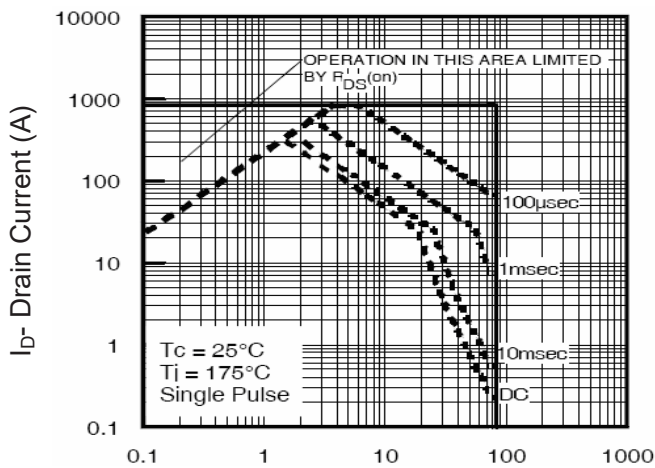




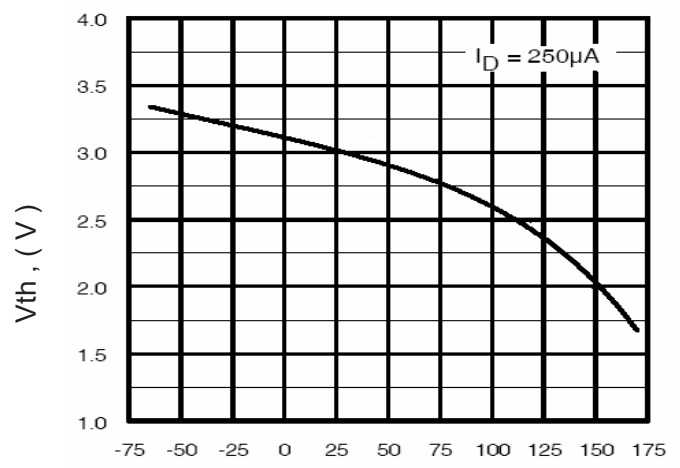
Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



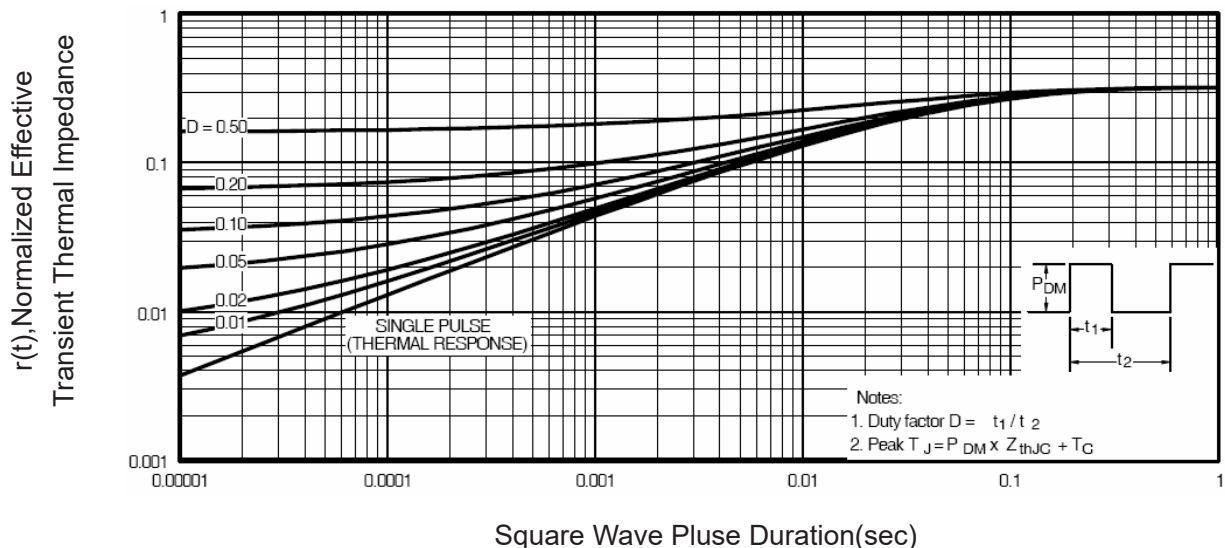
TJ-Junction Temperature(°C)
Figure 9 BV_{DSS} vs Junction Temperature



Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



TJ-Junction Temperature(°C)
Figure 10 V_{GS(th)} vs Junction Temperature



Square Wave Pulse Duration(sec)
Figure 11 Normalized Maximum Transient Thermal Impedance